Inventor: Seung Jong YOO For: "Method for Forming Semiconductor Device Bonding Pads" Attorney Docket No. 20063/10018 Sheet 1 of 2

Fig. 1

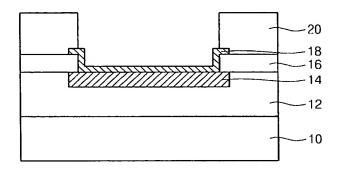


Fig. 2

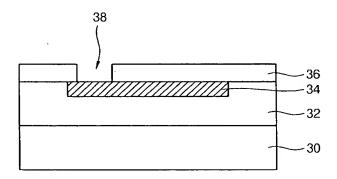
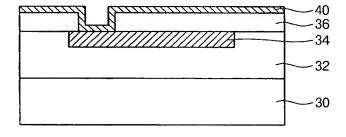


Fig. 3



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Fig. 4

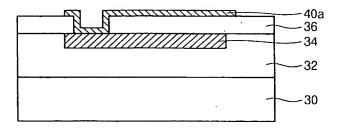


Fig. 5

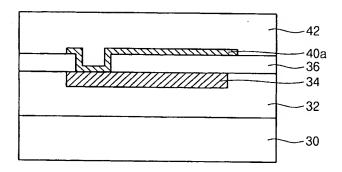


Fig. 6

